



Title of Change:	Update Notice to FPCN20930XA - Die Shrink- Guard Ring Width modification.
Proposed first ship date:	31 July 2017
Contact information:	Contact your local ON Semiconductor Sales Office or <SitiNurhaza.MohdRamli@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <MohdAzizi.Azman@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____

Change Sub-Category(s):			<input type="checkbox"/> Datasheet/Product Doc change
<input type="checkbox"/> Manufacturing Site Change/Addition	<input type="checkbox"/> Material Change		<input type="checkbox"/> Shipping/Packaging/Marking
<input checked="" type="checkbox"/> Manufacturing Process Change	<input checked="" type="checkbox"/> Product specific change		<input type="checkbox"/> Other: _____
Sites Affected:			
<input checked="" type="checkbox"/> All site(s)	<input type="checkbox"/> not applicable	<input type="checkbox"/> ON Semiconductor site(s) :	<input type="checkbox"/> External Foundry/Subcon site(s)

Description and Purpose:

This Update Notification announces to customers that Die Shrink- Guard Ring Width change as below:

Material to be changed	Before Change Description	After Change Description
Back metal thickness	12kA Au	8kA Au
Die Shrink- Guard Ring Width	2mils	1mils

FPCN20930XA was previously released to qualify Power Schottky Back Metal Thinning with Die Shrink.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
MBR0520LT1G	NRVB0540T1G
MBR0520LT1H	
MBR0520LT3G	
MBR0530T1G	
MBR0530T1H	
MBR0530T3G	
MBR0540T1G	
MBR0540T1H	
MBR0540T3G	
MBR130T1G	
MBR130T1H	
MBR130T3G	